

## ABSTRACT

The present invention provides a process for producing an epoxy resin molding material for semiconductor encapsulation, which is very low in voids generation; a molding material produced by the process; and a semiconductor device obtained by encapsulation with the molding material. That is, the present invention provides a process for producing an epoxy resin molding material for semiconductor encapsulation, which comprises premixing a composition containing at least an epoxy resin, a phenolic resin and an inorganic filler, then subjecting the resulting mixture to grinding by a grinder to obtain a powder having such a particle size distribution that the amount of particles having particle diameters of 250  $\mu\text{m}$  or more is 10% by weight or less, the amount of particles having particle diameters of 150  $\mu\text{m}$  to less than 250  $\mu\text{m}$  is 15% by weight or less, and the amount of particles having particle diameters of less than 150  $\mu\text{m}$  is 75% by weight or more, and thereafter subjecting the powder to melt kneading; a molding material produced by the process; and a semiconductor device obtained by encapsulation with the molding material.



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